NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE6990 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

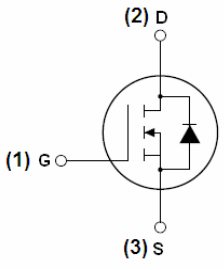
- V_{DS} =69V,I_D =88A
  $R_{DS(ON)}$ < 7.2mΩ @ V_{GS}=10V (Typ:6.2mΩ)
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

100% UIS TESTED!

100% ΔVds TESTED!



Schematic diagram

Marking and pin assignment

TO-220-3L top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE6990	NCE6990	TO-220	-	-	-

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	69	V
Gate-Source Voltage	VGS	±20	V
Drain Current-Continuous	ID	88	A
Drain Current-Continuous(TC=100℃)	ID (100℃)	62	A
Pulsed Drain Current	IDM	310	A
Maximum Power Dissipation	PD	160	W
Derating factor		1.1	W/℃
Single pulse avalanche energy (Note 5)	EAS	450	mJ
Operating Junction and Storage Temperature Range	TJ,TSTG	-55 To 175	℃

Thermal Characteristic

Thermal Resistance,Junction-to-Case (Note 2)	RθJC	0.9	℃/W

Electrical Characteristics (T_C=25℃unless otherwise noted)

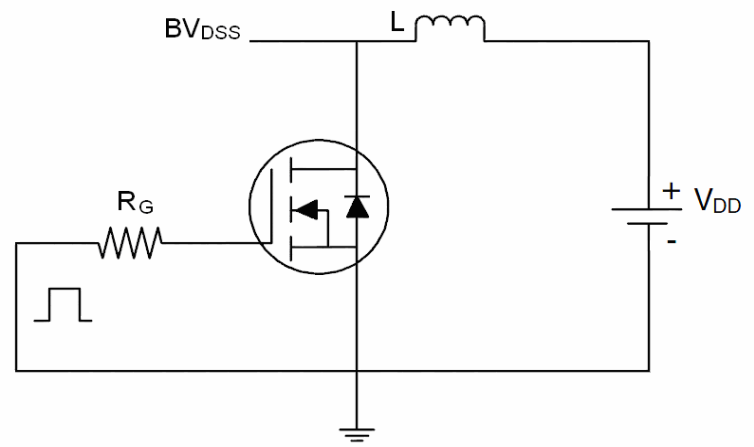
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BVDSS	VGS=0V ID=250μA	69	73	-	V
Zero Gate Voltage Drain Current	IDSS	VDS=69V,VGS=0V	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	V_{GS}=±20V,V_{DS}=0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	VGS(th)	VDS=VGS,ID=250μA	2	2.9	4	V
Drain-Source On-State Resistance	RDS(ON)	VGS=10V, ID=30A	-	6.2	7.2	mΩ
Forward Transconductance	gFS	VDS=10V,ID=100A	25	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	Clss	VDS=25V,VGS=0V, F=1.0MHz	-	3400	-	PF
Output Capacitance	Coss		-	310	-	PF
Reverse Transfer Capacitance	Crss		-	221	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	td(on)	VDD=30V,ID=2A,RL=15Ω VGS=10V,RG=2.5Ω	-	15	-	nS
Turn-on Rise Time	tr		-	11	-	nS
Turn-Off Delay Time	td(off)		-	52	-	nS
Turn-Off Fall Time	tf		-	13	-	nS
Total Gate Charge	Qg	VDS=30V,ID=30A, VGS=10V	-	94	-	nC
Gate-Source Charge	Qgs		-	16	-	nC
Gate-Drain Charge	Qgd		-	24	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	VSD	VGS=0V,IS=30A	-	-	1.2	V
Diode Forward Current (Note 2)	IS		-	-	78	A
Reverse Recovery Time	trr	TJ = 25°C, IF =75A di/dt = 100A/μs (Note3)	-	33		nS
Reverse Recovery Charge	Qrr		-	54		nC
Forward Turn-On Time	ton	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

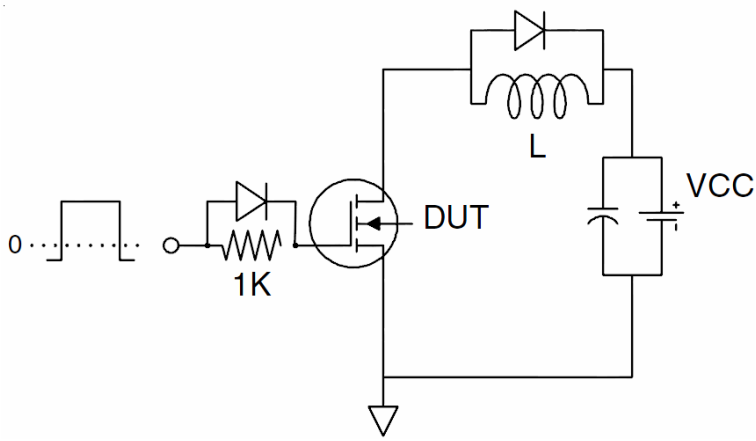
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. EAS condition:Tj=25℃,V_{DD}=35V,V_G=10V,L=0.5mH,Rg=25Ω

Test Circuit

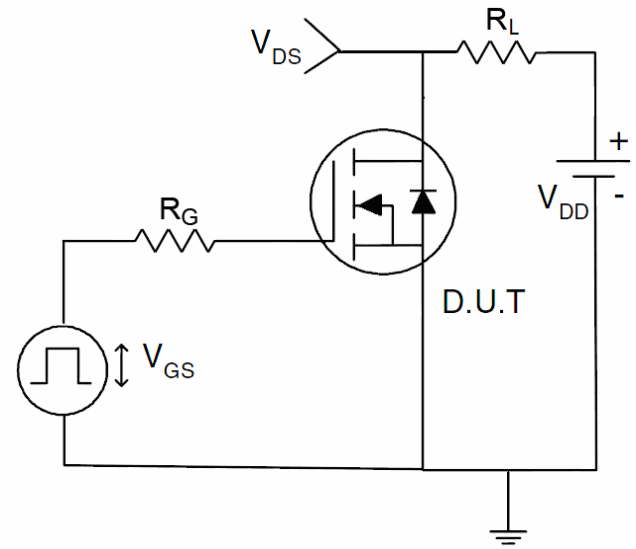
1) EAS test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit



Typical Electrical and Thermal Characteristics (Curves)

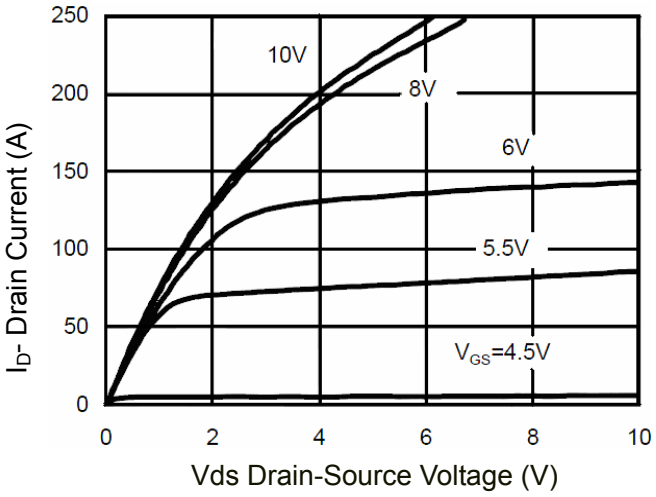


Figure 1 Output Characteristics

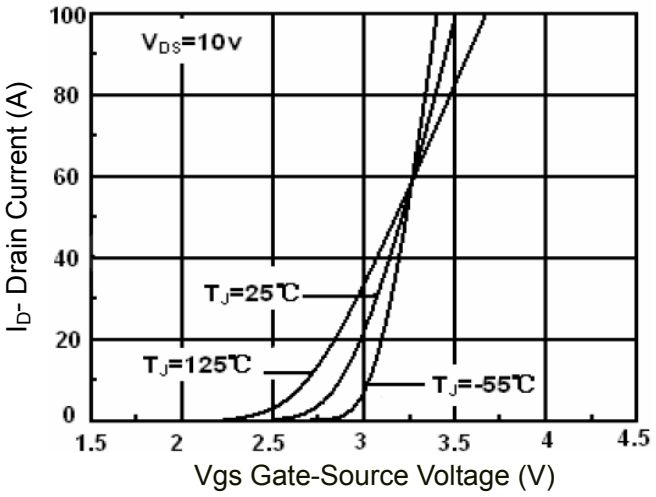


Figure 2 Transfer Characteristics

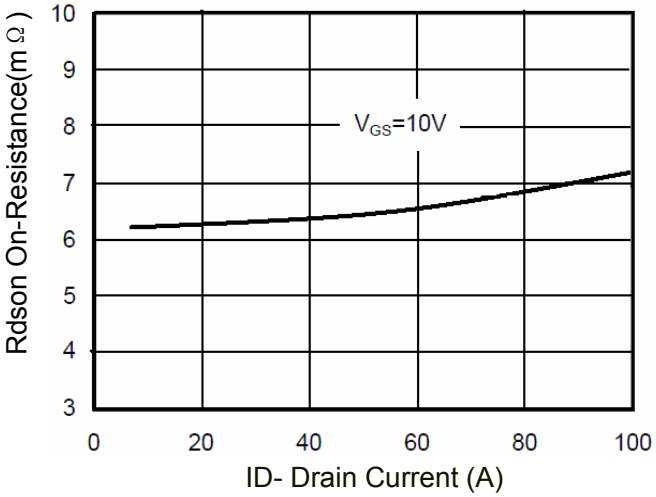


Figure 3 Rdson- Drain Current

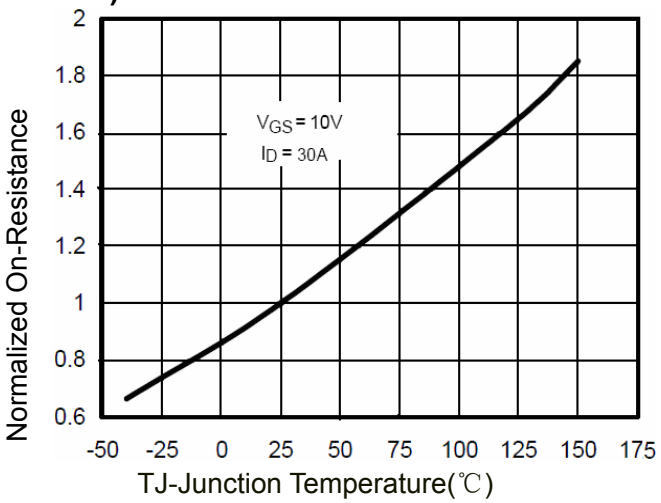


Figure 4 Rdson-JunctionTemperature

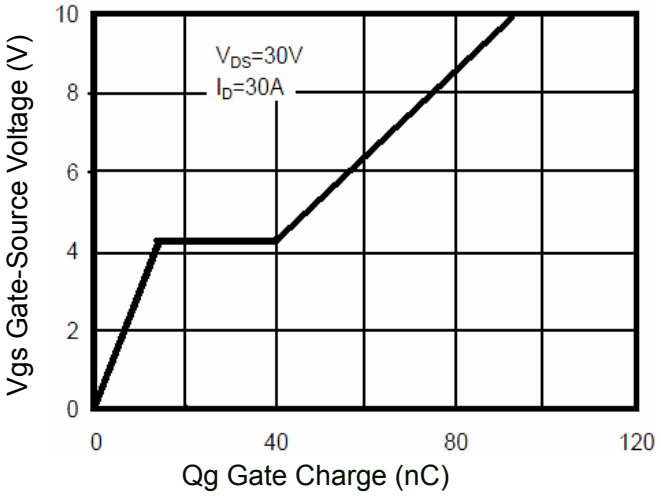


Figure 5 Gate Charge

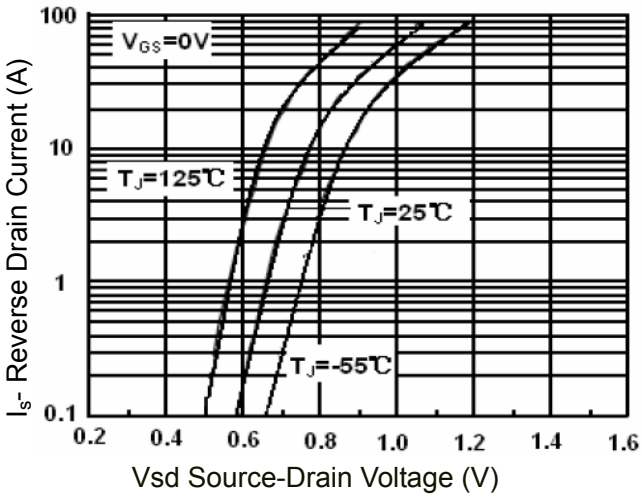


Figure 6 Source- Drain Diode Forward

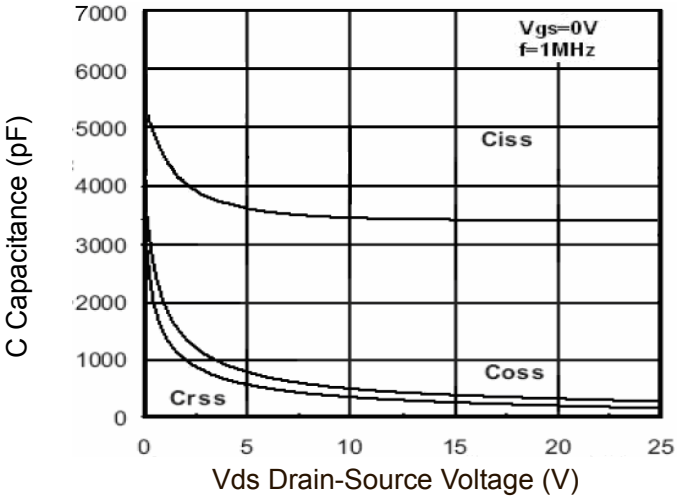


Figure 7 Capacitance vs Vds

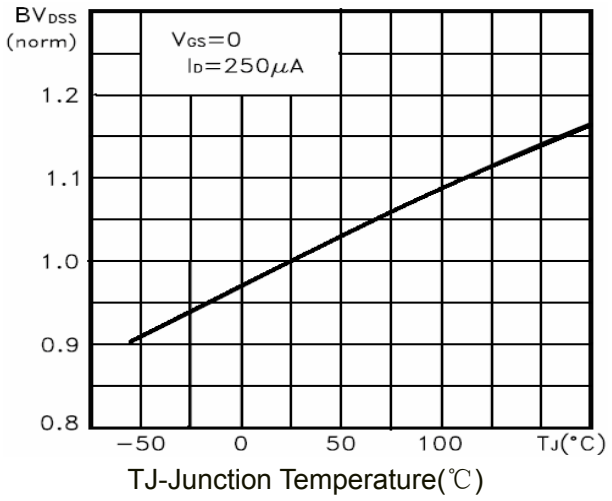


Figure 9 BV_{DSS} vs Junction Temperature

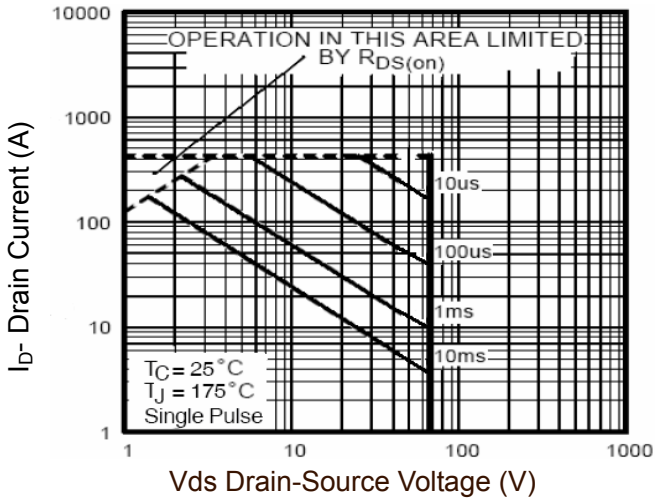


Figure 8 Safe Operation Area

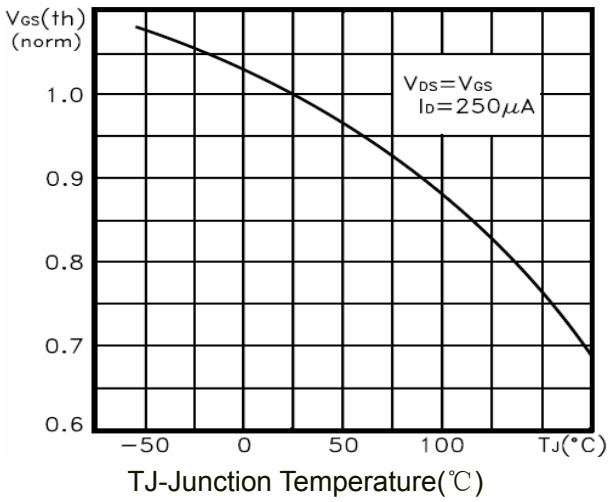


Figure 10 $V_{GS(th)}$ vs Junction Temperature

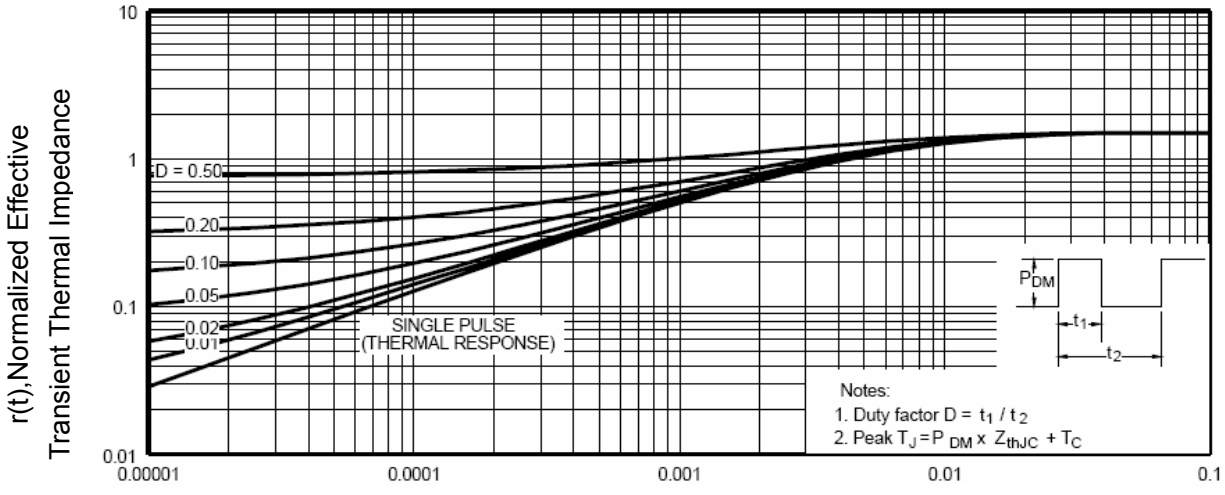
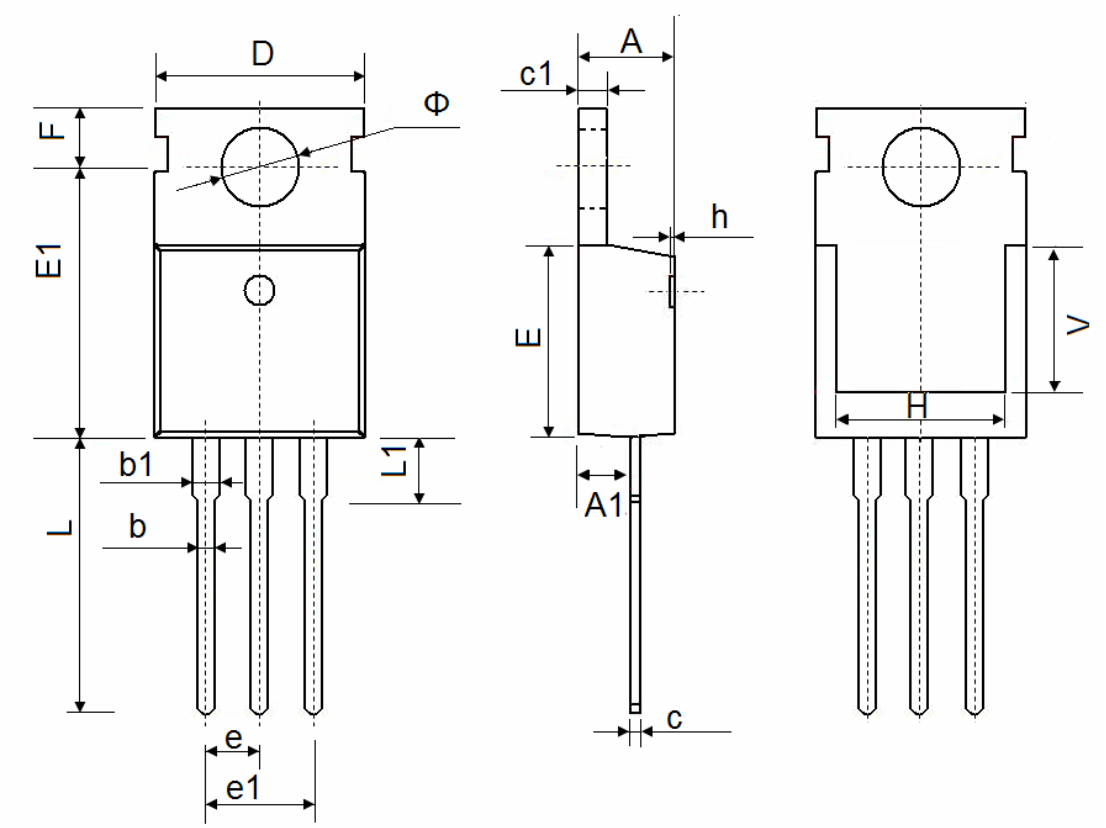


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-220-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	7.500 REF.		0.295 REF.	
Φ	3.400	3.800	0.134	0.150

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